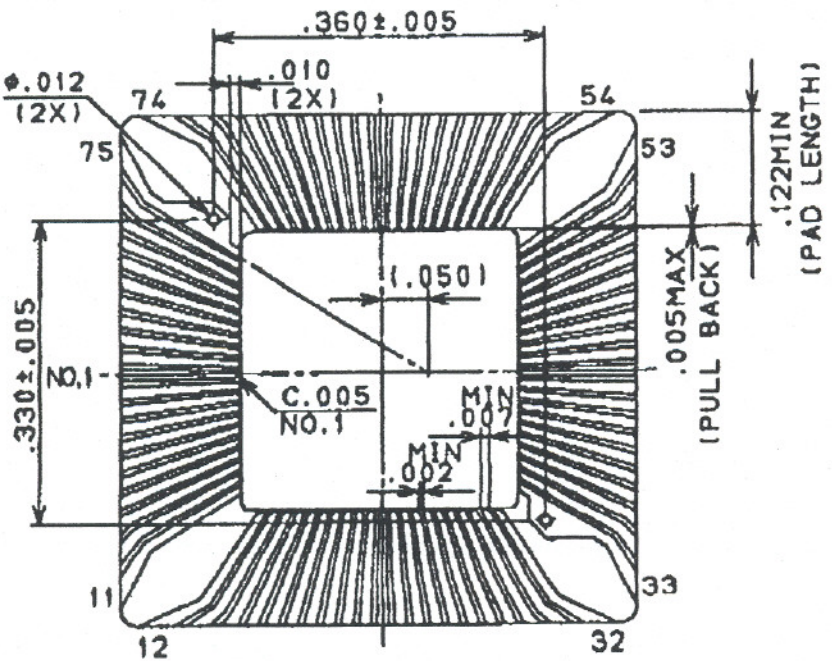
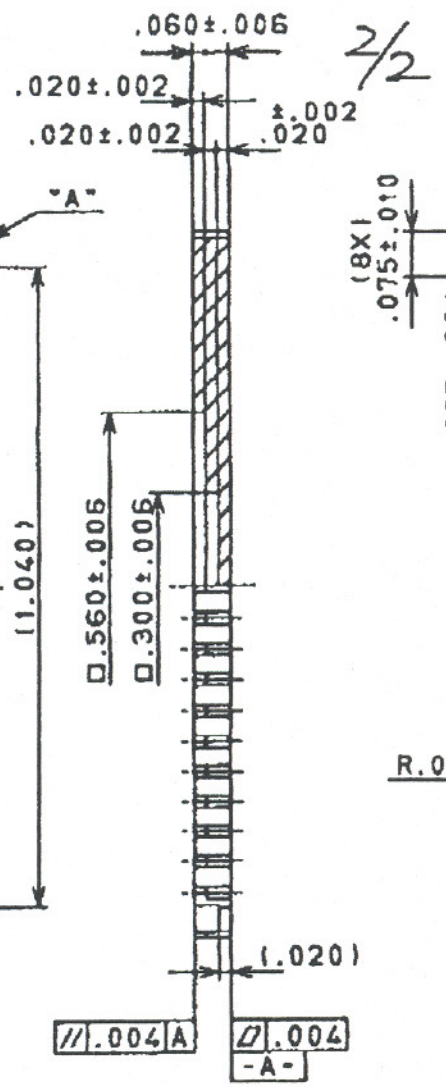
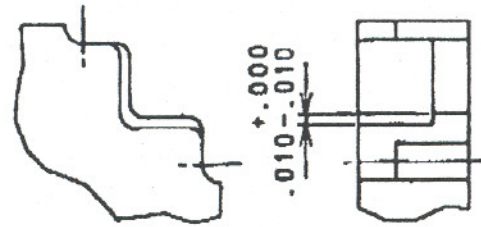


THIS METALLIZATION TO BE ELECTRICALLY CONNECTED TO THE SEAL RING.

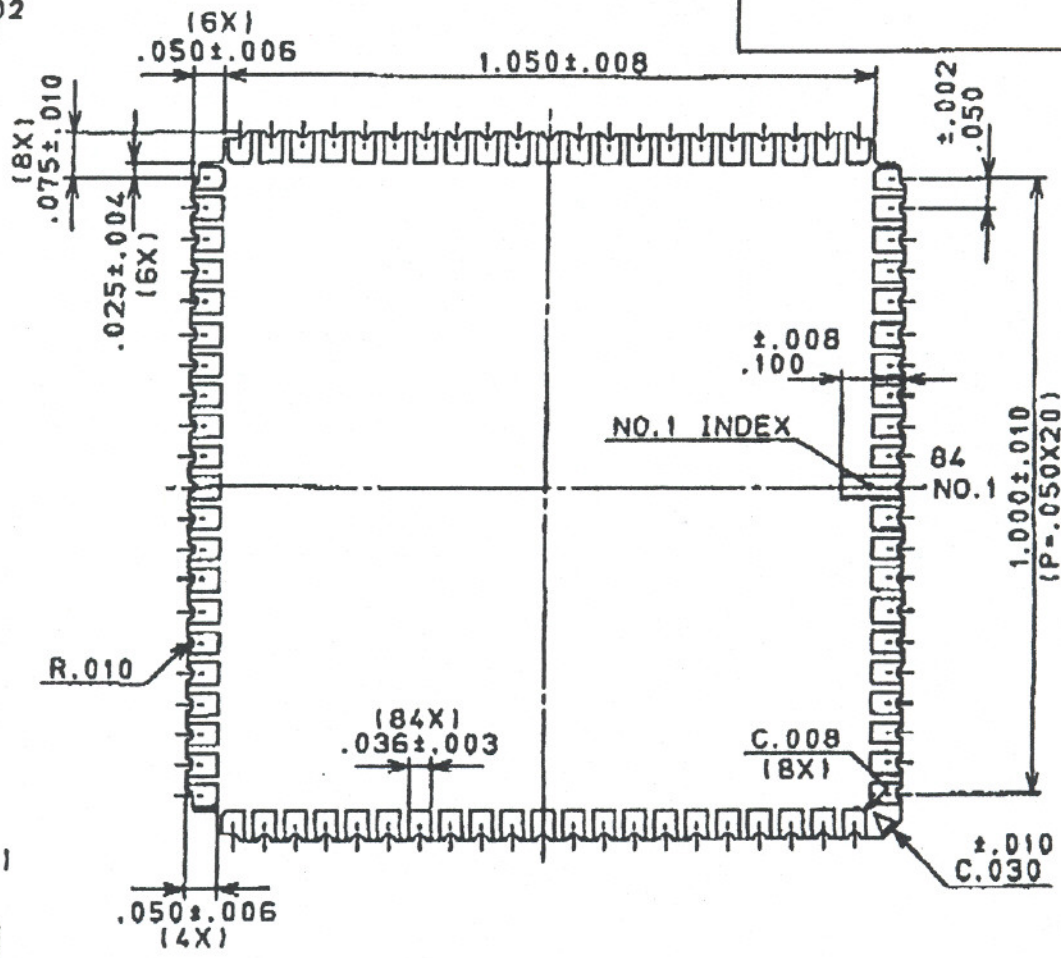


B/G PADS DETAIL



DETAIL "A"

002
20

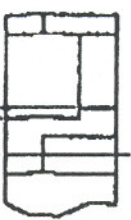


1/2

201

04

- NOTES: 1. GOLD PLATE 60μ INCHES MIN OVER 80μ INCHES MIN NICKEL.
 2. LEAD RESISTANCE: 300mΩ MAX.
 3. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.



3				B	RE DRAWING	REV. - 4 -1992
2				A	RE DRAWING	OCT-26 -1992
1	CERAMIC	BLACKINA		φ	NEW DRAWING	MAR-13 -1988
Rev	No	Mat	Description	Rev.	Description	Date
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1% N. L. T. 3 DECIMALS. 2X ± .01			DRAWN H. HASHIMOTO	NTS TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD.		
			CHECKED	TITLE B4 LEAD CHIP CARRIER		
			APPROVED JW	Dwg NO. IRK84F1-5004A		
			UNIT INCH	SIZE 1/2		
			SCALE			